Specification For LTCC 20dB Directional Coupler

Model Name : RCP3500Q20

Customer:	
Title:	
Name :	
APPROVED	
By Date :	-
Signature :	_

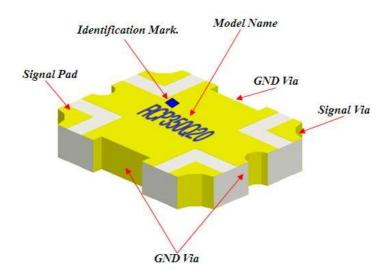
RN2 Technologies co., Ltd.

RN2 Technologies co., Ltd.	Issued Date :	
284-2, Galgot-ri, Jinwe-myeon,		
Pyeongtaek-si, Kyunggi-do, KOREA	Designed :	
Phone : (+82) 31 - 376 - 5400		
FAX : (+82) 31 - 376 - 9151	Approved :	



1. Description

1-1. Part number: RCP3500Q20(Denoted marking:RCP350Q20)



1-2. Features

- Directional Coupler 20dB
- Surface mount type
- Suitable for operation frequency 3400~3600MHz
- **RoHS** compliance
- High stability in temperature and humidity for LTCC base
- Low loss for Silver(Ag) conductor
- Miniature size and high power capability
- Lead-free alloy solderable
- Thermal expansion corresponding with common substrate

2. Electrical Specification

Freq.	Coupling	Directivity	Insertion Loss
(MHz)	(dB)	Max (dB)	min (dB)
3400-3600	20 ± 1	-20	-0.22
VSWR	Power Capacity	Characteristic Imp.	Operating Temp.
Max	Avg. (Watt)	(ohm)	(\mathcal{C})
1.2	80	50	-55 to +125

RN2 Technologies Co., Ltd.



3. Mechanical Specification

3-1. Outline Dimension

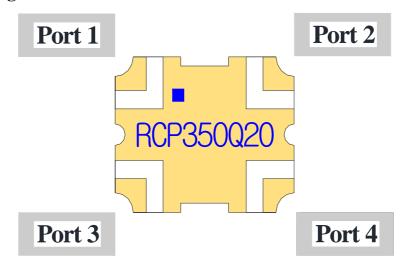
	PR	ROJECTION	NO.	DATI	E RF	EVISION & DESCR	IPTION	[-	SIGNA REVIEWED	
			1	2008.10.20		New-Drawing		r	KE VIEWED	CHECKED
			2	2012.04.20		Marking revision				
	4		3	201210112						
	 Inn Sur 	ID-type, Ceramic Base er signal circuits: Silverface plating: Gold(Aulerance is not cumulati	er(Ag) fini	8±0.08 g) condushed	2.54±0.08 5.08±0.15	1.10±0.08	0.60±0.00±0.00±0.00±0.00±0.00±0.00±0.00	3.18±0.08	2.54±0	08
				TAT.		UMIT TOTAL		I		
NO.		DESCRI	OIT			QUANTITY				

3-2. Weight

- $0.09 \pm 10\%$ Grams typical



4. Port Configuration



Configuration Port 1		Port 2	Port 3	Port 4
Case 1.	Case 1. Input		Coupled	Isolated
Case 2.	Output	Input	Isolated	Coupled
Case 3. Coupled		Isolated	Input	Output
Case 4.	Isolated	Coupled	Output	Input

^{*} Once Port 1 is determined, the other three ports are defined automatically.

5. Schematic Drawing





5/16

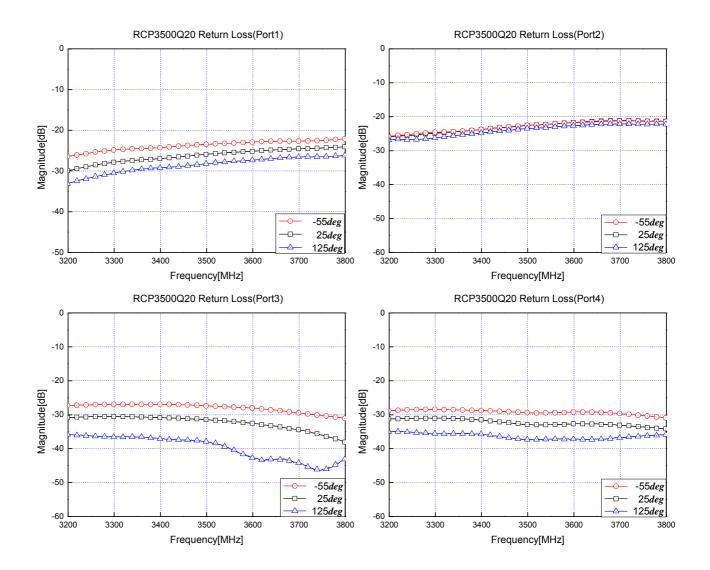
6. Typical Performance Data (25℃)

Freq.	Coupling	Out	IL	Directivity		Return Loss [dB]			
[MHz]	[dB]	[dB]	[dB]	[dB]	S11	S22	S33	S44	
3400	-20.52	-0.22	-0.18	-22.39	-26.94	-23.77	-30.89	-31.57	
3410	-20.52	-0.23	-0.19	-22.40	-26.84	-23.63	-30.93	-31.72	
3420	-20.51	-0.21	-0.17	-22.27	-26.77	-23.45	-30.99	-31.84	
3430	-20.51	-0.21	-0.17	-22.46	-26.66	-23.36	-30.99	-31.97	
3440	-20.51	-0.19	-0.15	-22.33	-26.53	-23.27	-31.10	-32.15	
3450	-20.51	-0.19	-0.15	-22.32	-26.43	-23.16	-31.13	-32.29	
3460	-20.52	-0.17	-0.13	-22.20	-26.32	-23.09	-31.17	-32.46	
3470	-20.48	-0.14	-0.10	-22.23	-26.20	-22.97	-31.23	-32.58	
3480	-20.50	-0.13	-0.09	-22.34	-26.10	-22.81	-31.30	-32.70	
3490	-20.51	-0.13	-0.09	-22.20	-26.01	-22.67	-31.41	-32.85	
3500	-20.52	-0.14	-0.10	-22.16	-25.89	-22.59	-31.44	-32.90	
3510	-20.50	-0.14	-0.10	-22.15	-25.80	-22.50	-31.59	-32.97	
3520	-20.53	-0.16	-0.12	-22.29	-25.69	-22.40	-31.60	-32.98	
3530	-20.54	-0.19	-0.15	-22.06	-25.63	-22.37	-31.68	-32.94	
3540	-20.54	-0.21	-0.17	-22.17	-25.53	-22.25	-31.77	-33.00	
3550	-20.55	-0.23	-0.19	-22.24	-25.47	-22.16	-31.92	-32.96	
3560	-20.56	-0.23	-0.19	-22.13	-25.40	-22.07	-31.96	-32.89	
3570	-20.56	-0.24	-0.20	-22.18	-25.33	-21.94	-32.13	-32.88	
3580	-20.55	-0.22	-0.18	-22.22	-25.26	-21.84	-32.29	-32.73	
3590	-20.56	-0.23	-0.19	-22.19	-25.19	-21.75	-32.45	-32.72	
3600	-20.54	-0.18	-0.14	-22.20	-25.14	-21.69	-32.59	-32.71	

^{*} Data with PCB and Connector Loss (3.5 GHz = 0.1 dB)

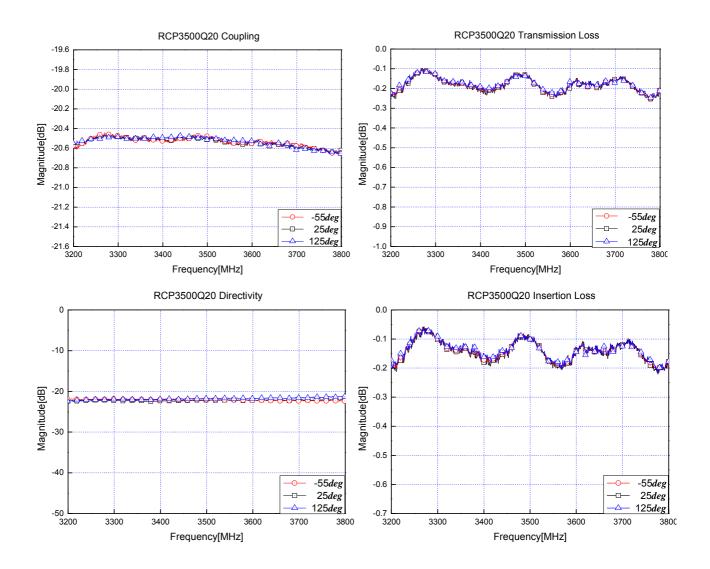


. Operation Temperature Curve (a)



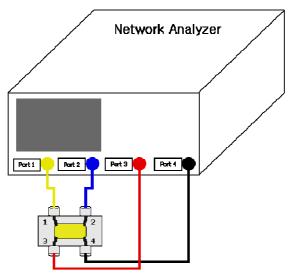


8. Operation Temperature Curve (b)





9. Test Method



- Refer to 'Case 1' of '4. Port Configuration' on page 4
- Have the network analyzer calibrated properly.
- Measure the data of **Coupling** through port 1 to port 3. (S31)
- Measure the data of **Transmission** through port 1 to port 2. (S21)
- Measure the data of **Isolation** through port 1 to port 4. (S41)
- Calculate the **Insertion Loss** and **Amplitude Balance** of coupler on the below power method formula.

	S-Parameter[dB]	Power Method[dB]
Coupling	S31	$10 \cdot \log \left(rac{P_{cou}}{P_{in}} ight)$
Transmission Loss	S21	$10 \cdot \log \left(\frac{P_{out}}{P_{in}} \right)$
Isolation	S41	$10 \cdot \log \left(\frac{P_{iso}}{P_{in}} \right)$
Insertion Loss		$10 \cdot \log \left(\frac{P_{in}}{P_{cou} + P_{out}} \right)$
Directivity		$10 + \log \left(rac{P_{cou}}{P_{iso}} ight)$

P_{in}: Power of Input Port

P_{out}: Power of Output Port

 P_{cou} : Power of Coupling Port

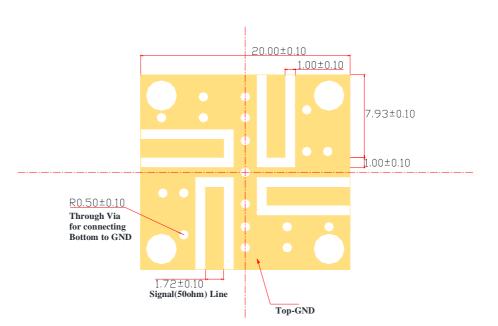
P_{iso}: Power of Isolated Port



9 / 16

10. Measurement board layout

ı	PROJECTION		No.	DATE	REVISION & DESCRIPTION	SIGNA	ATURE
ı			No. DATE REVISION & DESCRIPTION		REVIEWED	CHECKED	
			1	2008.06.23	New - Drawing		
	$\langle \langle \rangle \rangle$		2				
ı			3				
ı							



NOTE. Signal line width is shown for the conditions of;

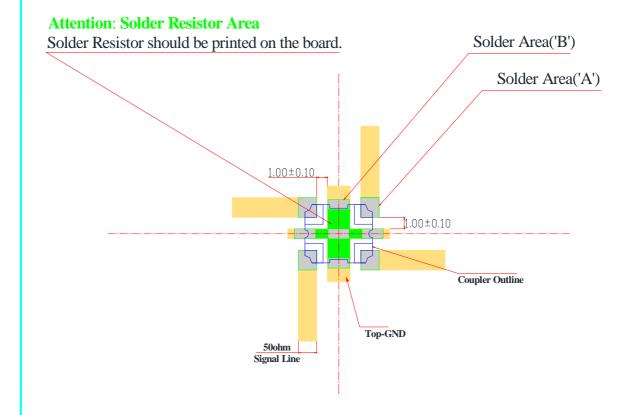
- 1. RF-35 (Taconic) board
- 2. Dielectric contance 3.5
- 3. Board thickness 0.8mm
- 4. Copper thickness 1 oz.

No.		DESCRIPTION		UNIT	TOTAL	PERUNIT	TOTAL			
140.	DESCRIPTION			QUA	YTITY					
		O sing Country Management Board Outline	DNA DWG N	08-0623-01		SCALE				
11	TLE	Q size Coupler-Measuremnet Board Outline	RN2 DWG No.		06-0023	- 01	SIZE	A4	DIMENSION	mm



11. Recommended PCB layout and Solder mask pattern

PROJECTION	No.	DATE	REVISION & DESCRIPTION	SIGNA	ATURE
PROJECTION	INO.	DATE	REVISION & DESCRIPTION	REVIEWED	CHECKED
+ —	1	2009.02.18	New - Drawing		
*	3				



NOTE.

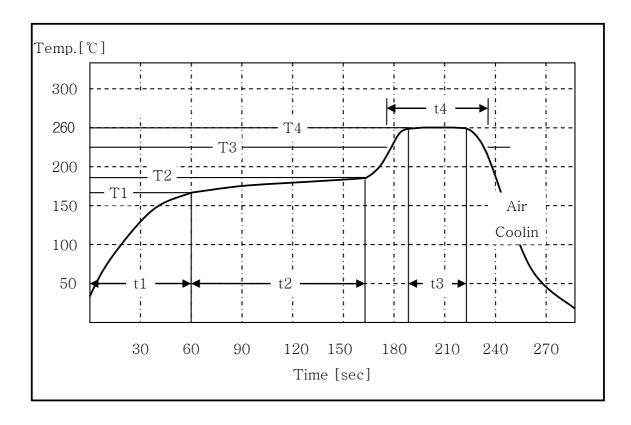
1. Test Solder Cream: SAC-305 (Alpa Metal)

Lead Free Solder Alloy: Sn/Ag/Cu Ratio Of 96.5/3.0/0.5
 Solder Area ('A') Demension: 1.72 mm by 1.72 mm
 Solder Area ('B') Demension: 2.0 mm by 0.88 mm

No.		DESCRIPTION		UNIT TOTAL	PERUNIT	TOTAL			
140.	DESCRIPTION		QUANTITY						
an a		O size - Recommended Solder Quantity	DNA DWG N	09-0218	01	SCALE			
11	TLE	&Area	RN2 DWG No.	09-0210	- 01	SIZE	A4	DIMENSION	mm



12. Reflow profile



	Ramp Up	Pre-Heating	Peak	Soaking
Temp. [℃]	T1:160±5℃	T2:180±5℃	T4:260±5℃	T3:230±5℃
Time [sec]	t1:60±5sec	t2:100±15sec	t3:30±5sec	t4:60±10sec



13. Using note for LTCC Couplers

I. Be careful when transporting

- A. Excessive stress or shock may make products broken or cracked due to the nature of ceramics structure.
- B. The products cracked or damaged on terminals may have their property changed.

II. Be careful during storage

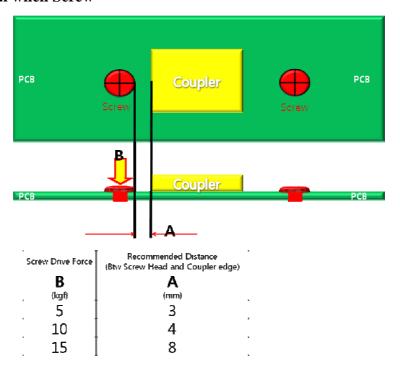
- A. Store the products in the temperature of -55 \sim 125 $^{\circ}$ C
- B. Keep the humidity at $45 \sim 75\%$ around the products.
- C. Prevent corrosive gas (Cl₂, NH₃, SO_X, NO_X, etc.) from contacting the products.
- D. It is recommended to use the products within 6 months of receipt. If the period exceeds 6 months, solderability may need to be verified.

III. Be careful when soldering

- A. All the ground terminals, IN and OUT pad of coupler should be soldered on the ground plane of the PCB.
- B. Products may be cracked or broken by uneven forces from a claw or suction device.
- C. Mechanical stress by any other devices may damage products when positioning them on PCB.
- D. A dropped product is recommended not to be used.
- E. Soldering must be carried out by the condition of specification sheet.
- F. Any couplers which are de-soldered from PCB should not be used again.

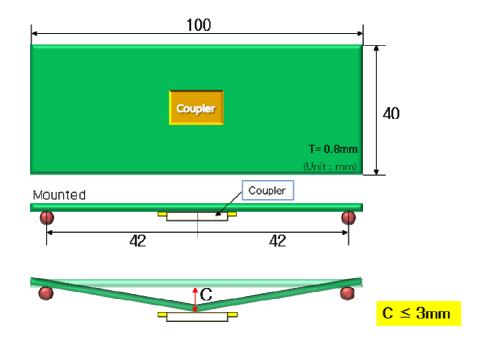


IV. Be careful when Screw



V. Be careful when SMD or Assembly

- A. LTCC couplers require appropriate measures to avoid its base PCB from warping.
- **B.** PCB excessively warping over defined standard may result in crack of LTCC couplers potentially.





14. Packaging

PROJECTION	No. DATE	REVISION & DESCRIPTION	V	SIGNA REVIEWED	
1 -	1 2008.08.04	New Drawing		TEL TE TE	
	2				
	3				
	P0=4±0.1 P2=2±0.1	AO AO	MINNO CO'	t KO	
	•••	Feed Direction			
330 330		330			
<u> </u>		A0 5.5±0.10	Е	1.75±0	.10
		B0 6.8±0.10	F	7.50±0	.10
0		D0 1.55+0.05	t	0.30±0	
Starndard Packaging Qua	antity: 4,000 PCS /	K0 1.87±0.10		16.0±0	
No. DESCRIPT	TON	UNIT TOTAL			
DESCRIPT	ION	QUANTITY	I.E.		
TITLE Q-Size Packaging Dir	mension RN2 DW	G No. $08-0804-04 \qquad \frac{\text{SCA}}{\text{SIZ}}$		Dimension	mm



15. Environmental Reliability

ITEM	PROCEDURE	REQUIREMENTS/RESULT
Temperature Cycle (Thermal Shock)	 One Cycle: 30 min Step1: 125 ± 5 °C for 15 min Step2: -55 ± 5 °C for 15 min Approach high or low temperature in 10 seconds Number of Cycles: 100 Normal temperature for 1 hour 	Meet the electrical Specification after test
Solderability	1. Solder: 230 ± 5 °C for 5 ± 1 sec.	1. More than 85% of the I/O electrode pad shall be covered with solder.
Heat Resistance	1. Temperature : 100 ± 2 °C 2. Duration : 96 ± 2 hours	Meet the electrical Specification after test
Low Temp. Resistance	1. Temperature : -55 ± 5 °C 2. Duration : 24 ± 2 hours	Meet the electrical Specification after test
Vibration Resistance	 Frequency: 5~ 15MHz Acceleration: 10g Sweep Time: 0.1 oct/min, 15min/axis Axis: X, Y and Z direction 	No appearance damage Meet the electrical Specification after test
Humidity Resistance	1. One Cycle: Step1:increase Temperature -25~65°C for 2hours with humidity 85% Step2:Maintain for 4 hour after increasing Humidity 90% to 95% Step3: Decrease Temperature 65°C to 25°C 2. Number of Cycles: 10 3. Maintain for 3hour after decreasing temperature -10°C	Meet the electrical Specification after test
Drop Shock	1. Dropped onto hard wood from height of 50 cm for 5 times; each x, y and z direction except I/O direction.	No appearance damage Meet the electrical Specification after test



16. RoHS test result

RN2 Technologies warrants and represents as follows.

Test Report No. F690501/LF-CTSGP06-16067 Date: June 29, 2008 Page 2 of 3

Sample No. : GP06-16067.001
Sample Description : LTCC COUPLER

Style/Item No. : N/A

Comments : Materials are ceramics, Ag.

Heavy Metals

Test items	Unit	Test Method	MDL	Results
Cadmlum(Cd)	mg/kg	US EPA 3050B(1996), US EPA 6010B(1996), ICP	0.5	N.D.
Lead (Pb)	mg/kg	US EPA 3050B(1996), US EPA 6010B(1996), ICP	5	N.D.
Mercury (Hg)	mg/kg	US EPA 3052(1996), US EPA 6010B(1996), ICP	2	N.D.
Hexavalent Chromium (Cr VI)	mg/kg	US EPA 3060A(1996), US EPA 7196A(1992), UV	1	N.D.

Flame Retardants-PBBs/PBDEs

Test items	Unit	Test Method	MDL	Results
Monobromoblphenyl	mg/kg	US EPA 3540C, GC/MS	- 5	N.D.
Dibromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tribromoblphenyl	mg/kg	US EPA 3540C, GC/MS		N.D.
Tetrabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Pentabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	- 5	N.D.
Hexabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Heptabromobiphenyl	mg/kg	US EPA 3540C, GC/MS		N.D.
Octabromoblphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Nonabromoblphenyl	mg/kg	US EPA 3540C, GC/MS	- 5	N.D.
Decabromobiphenyl	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Monobromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS		N.D.
Dibromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tribromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Tetrabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Pentabromodiphenyi ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Hexabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Heptabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	- 5	N.D.
Octabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Nonabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.
Decabromodiphenyl ether	mg/kg	US EPA 3540C, GC/MS	5	N.D.

NOTE: (1) N.D. = Not detected.(<MDL)

(2) ppm = mg/kg

(3) MDL = Method Detection Limit

(4) - = No regulation

(5) ** = Qualitative analysis (No Unit)

(6) Negative = Undetectable / Positive = Detectable

This Test Report is issued by the Company subject to its General Conditions of Service printed overleaf. Attention is drawn to the Imitations of liability, indemnification and jurisdictional issues defined therein. The secuts shown in this test report refer only to the sample (s) bested unless otherwise stated. This Test Report cannot be reproduced, except in full, without prior written permission of the Company.